DATA SHEET

NEC

MOS FIELD EFFECT TRANSISTOR

μPA1723

SWITCHING
N-CHANNEL POWER MOS FET
INDUSTRIAL USE

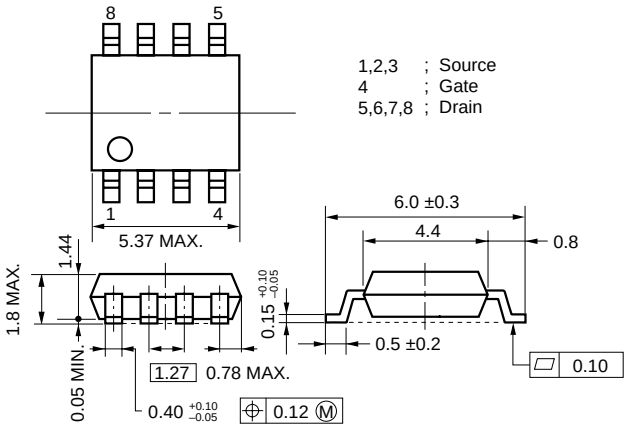
DESCRIPTION

The μPA1723 is N-Channel MOS Field Effect Transistor designed for power management switch.

FEATURES

- Low on-state resistance
  $R_{DS(on)1}$ = 6.7 mΩ MAX. (V_{GS} = 4.5 V, I_D = 7.0 A)
  $R_{DS(on)2}$ = 7.4 mΩ MAX. (V_{GS} = 4.0 V, I_D = 7.0 A)
  $R_{DS(on)3}$ = 8.7 mΩ MAX. (V_{GS} = 2.5 V, I_D = 7.0 A)
- Low C_{iss} : C_{iss} = 3800 pF TYP.
- Built-in G-S protection diode
- Small and surface mount package (Power SOP8)

PACKAGE DRAWING (Unit : mm)



ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA1723G	Power SOP8

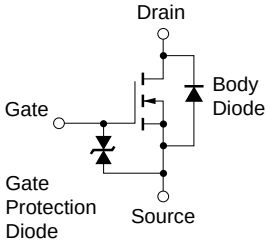
ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, All terminals are connected.)

Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	20	V
Gate to Source Voltage (V_{DS} = 0 V)	V_{GSS}	±12	V
Drain Current (DC)	$I_{D(DC)}$	±13	A
Drain Current (pulse) Note1	$I_{D(pulse)}$	±52	A
Total Power Dissipation (T_A = 25°C) Note2	P_T	2.0	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{stg}	–55 to + 150	°C

Notes 1. PW ≤ 10 μs, Duty Cycle ≤ 1 %

2. Mounted on ceramic substrate of 1200 mm^2 x 2.2mm

EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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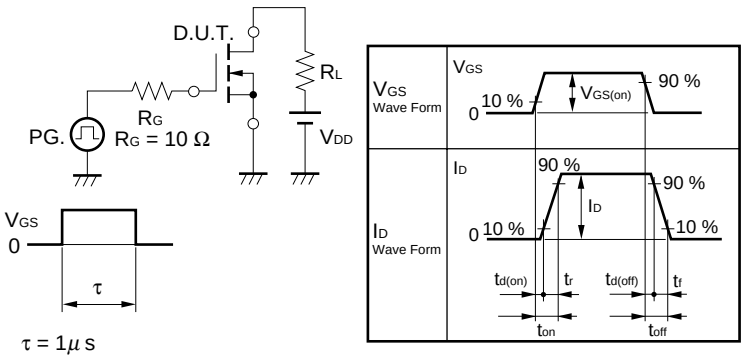
The mark ★ shows major revised points.

ELECTRICAL CHARACTERISTICS (T_A = 25 °C, All terminals are connected.)

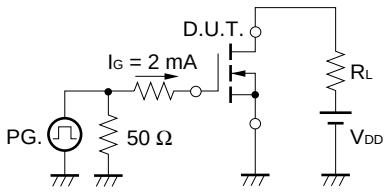
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = 4.5 V, I_D = 7.0 A		5.4	6.7	mΩ
	$R_{DS(on)2}$	V_{GS} = 4.0 V, I_D = 7.0 A		5.5	7.4	mΩ
	$R_{DS(on)3}$	V_{GS} = 2.5 V, I_D = 7.0 A		6.5	8.7	mΩ
Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = 10 V, I_D = 1 mA	0.5	0.9	1.5	V
Forward Transfer Admittance	$\|y_{fs}\|$	V_{DS} = 10 V, I_D = 7.0 A	15.0	32		S
Drain Leakage Current	I_{DSS}	V_{DS} = 20 V, V_{GS} = 0 V			10	μA
Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±12 V, V_{DS} = 0 V			±10	μA
Input Capacitance	C_{iss}	V_{DS} = 10 V		3800		pF
Output Capacitance	C_{oss}	V_{GS} = 0 V		1200		pF
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		700		pF
Turn-on Delay Time	$t_{d(on)}$	I_D = 7.0 A		70		ns
Rise Time	t_r	$V_{GS(on)}$ = 4.5 V		440		ns
Turn-off Delay Time	$t_{d(off)}$	V_{DD} = 10 V		230		ns
Fall Time	t_f	R_G = 10 Ω		300		ns
Total Gate Charge	Q_G	I_D = 13 A		47.0		nC
Gate to Source Charge	Q_{GS}	V_{DD} = 16 V		11.0		nC
Gate to Drain Charge	Q_{GD}	V_{GS} = 4.5 V		12.0		nC
Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 13.0 A, V_{GS} = 0 V		0.75		V
Reverse Recovery Time	t_{rr}	I_F = 13.0 A, V_{GS} = 0 V		68		ns
Reverse Recovery Charge	Q_{rr}	di/dt = 100 A/ μs		70		nC

TEST CIRCUIT 1 SWITCHING TIME



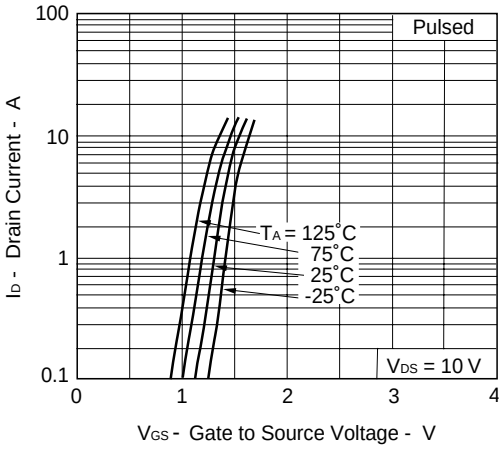
τ = 1μ s
Duty Cycle ≤ 1 %

TEST CIRCUIT 2 GATE CHARGE

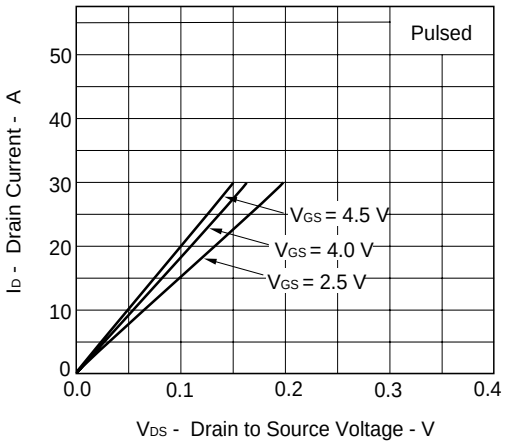


TYPICAL CHARACTERISTICS (T_A = 25°C)

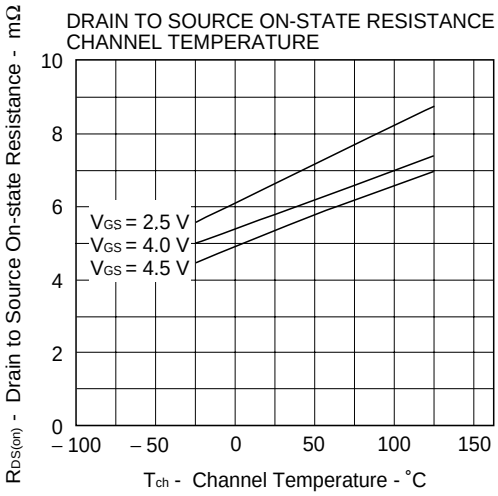
FORWARD TRANSFER CHARACTERISTICS



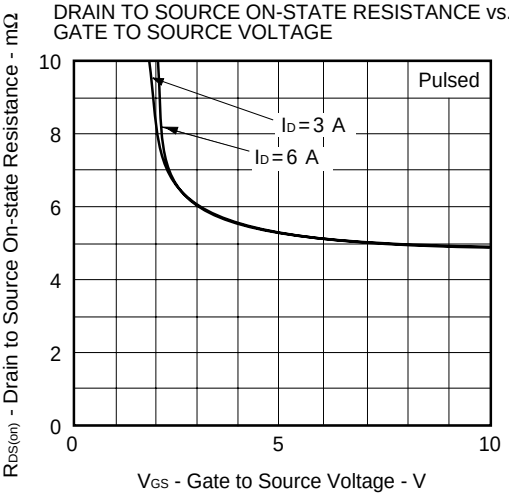
DRAIN CURRENT vs.
DRAIN TO SOURCE VOLTAGE



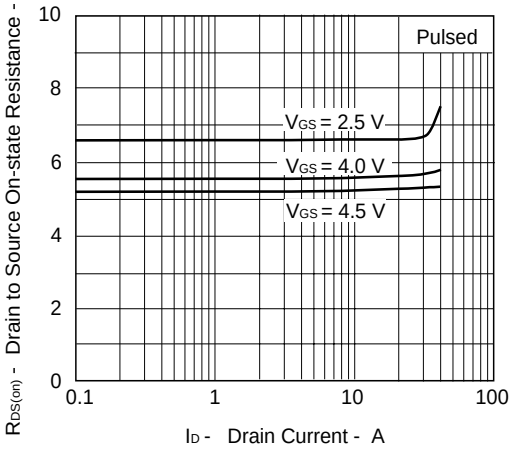
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
CHANNEL TEMPERATURE



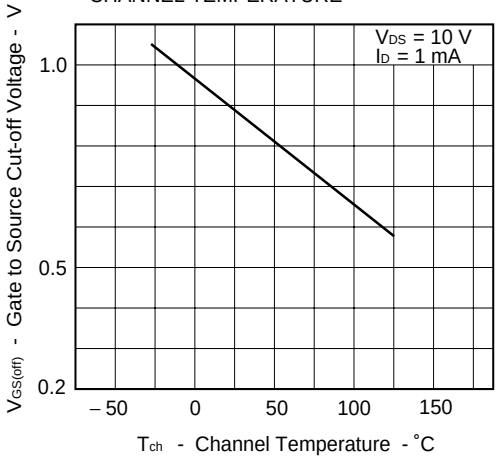
DRAIN TO SOURCE ON-STATE RESISTANCE vs.
GATE TO SOURCE VOLTAGE



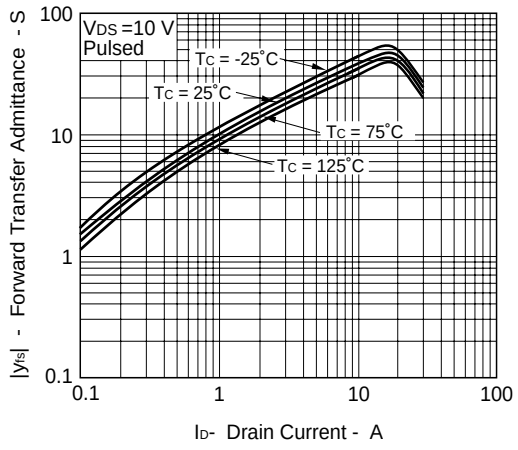
DRAIN TO SOURCE ON-STATE
RESISTANCE vs. DRAIN CURRENT



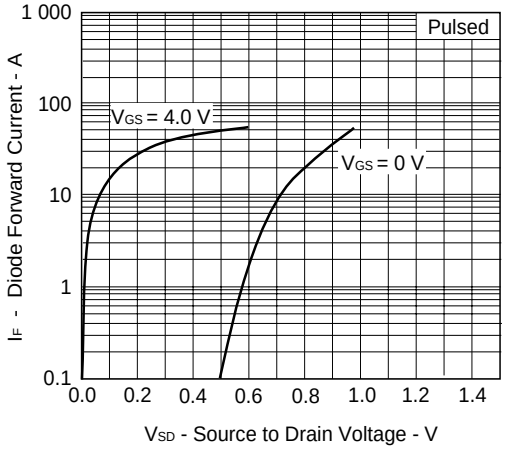
GATE TO SOURCE CUT-OFF VOLTAGE vs.
CHANNEL TEMPERATURE



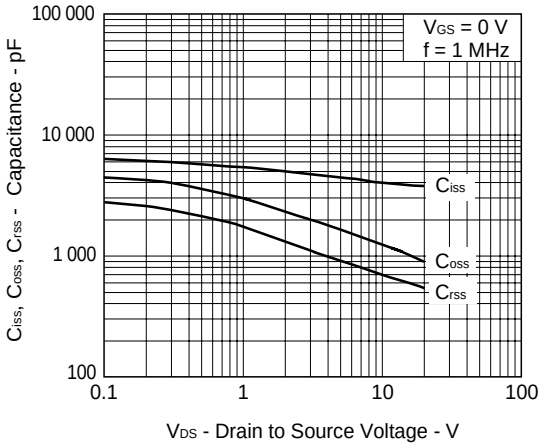
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



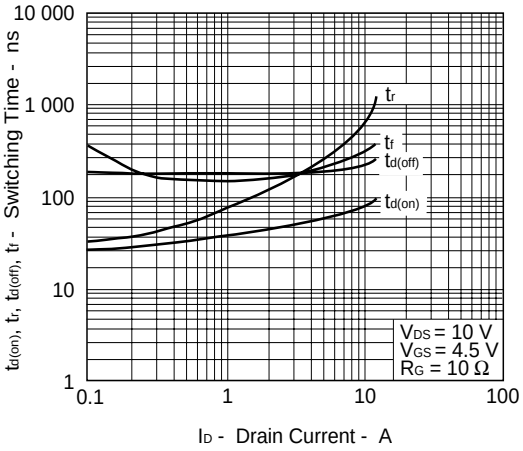
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

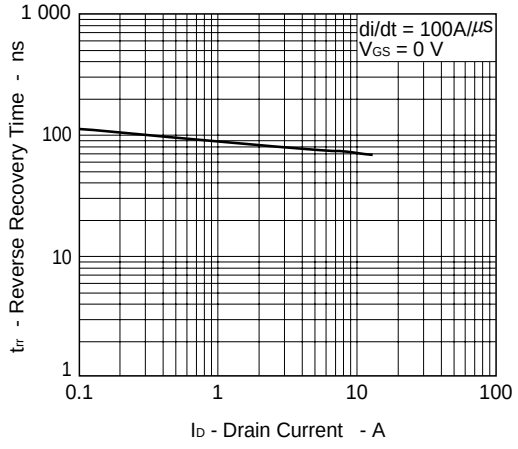


SWITCHING CHARACTERISTICS

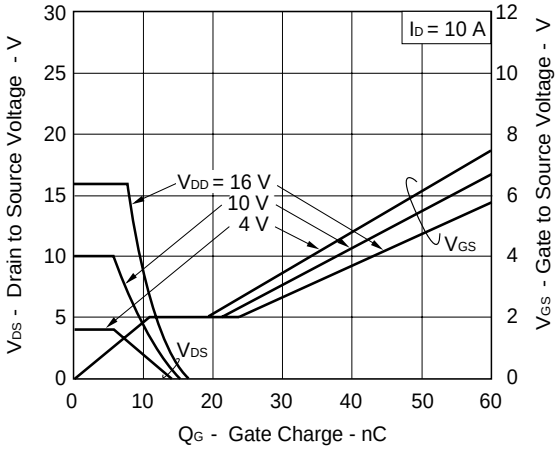


Remark
Mounted on ceramic substrate of 1200 mm^2 x 2.2 mm

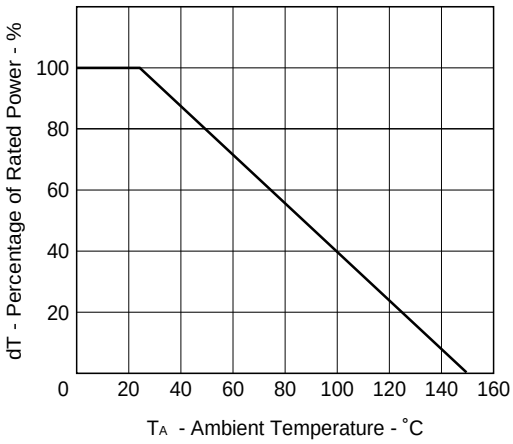
REVERSE RECOVERY TIME vs. DRAIN CURRENT



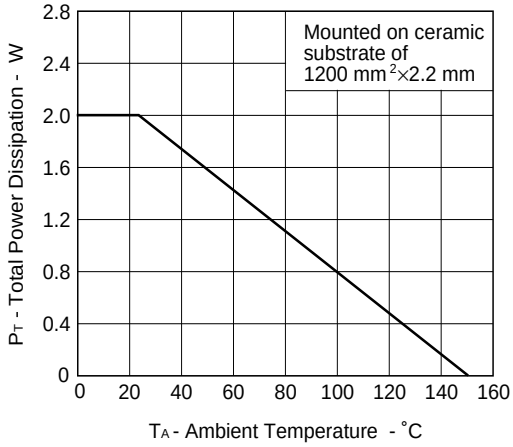
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



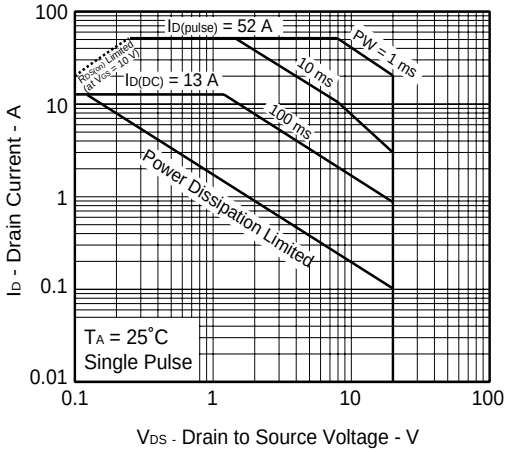
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE

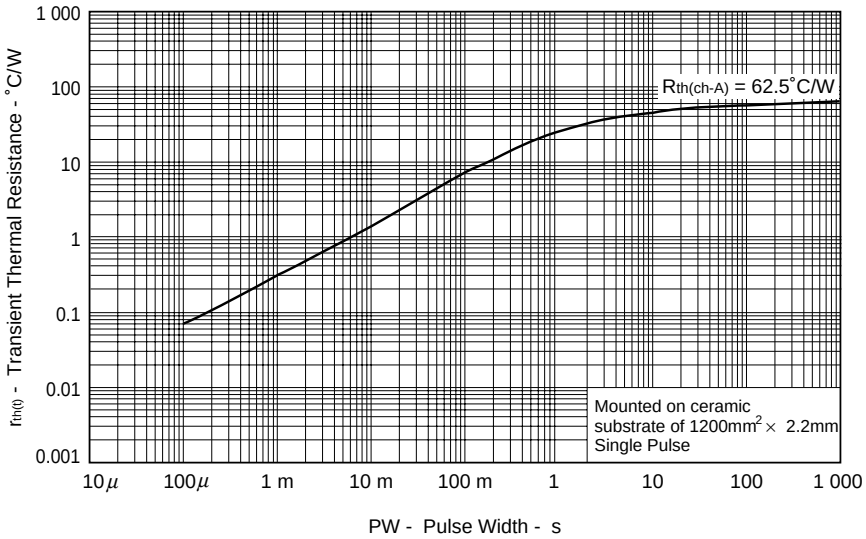


★ FORWARD BIAS SAFE OPERATING AREA



Remark
Mounted on ceramic substrate of 1200 mm^2 x 2.2 mm

TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



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